

DIODE LEADLESS CHIP CARRIER

DLCC3

- Light Weight Hermetic Ceramic Surface Mount Package is designed as a drop In replacement for "MELF-5.7 (D-5B)" / "E-MELF" packages†
- Designed For High Reliability Military, Aerospace and Space Applications



ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated)

V_{RMS}	Maximum Peak RMS Voltage	>1.6KV
V_{DC}	Maximum DC Blocking Voltage	>2KV
I	Maximum DC Output Current	8A

PACKAGE MASS

Gold Plated Solder Pad Finish typically 150mg
63Sn/37Pb Solder Tin Dipped typically <160mg

Comparison with similar D-5B / E-MELF packages shows significant weight saving.
For example:

1N5811US = 539mg
1N4954US = 540mg

† The DLCC3 package design takes full advantage of the proven high reliability pedigree of the HTCC surface mount packaging technology, which is easily integrated for automated assembly. Semelab has taken the existing standards for ceramic surface mount package manufacture and added additional design features to enhance thermal performance, to present a competitive alternative for high reliability applications.

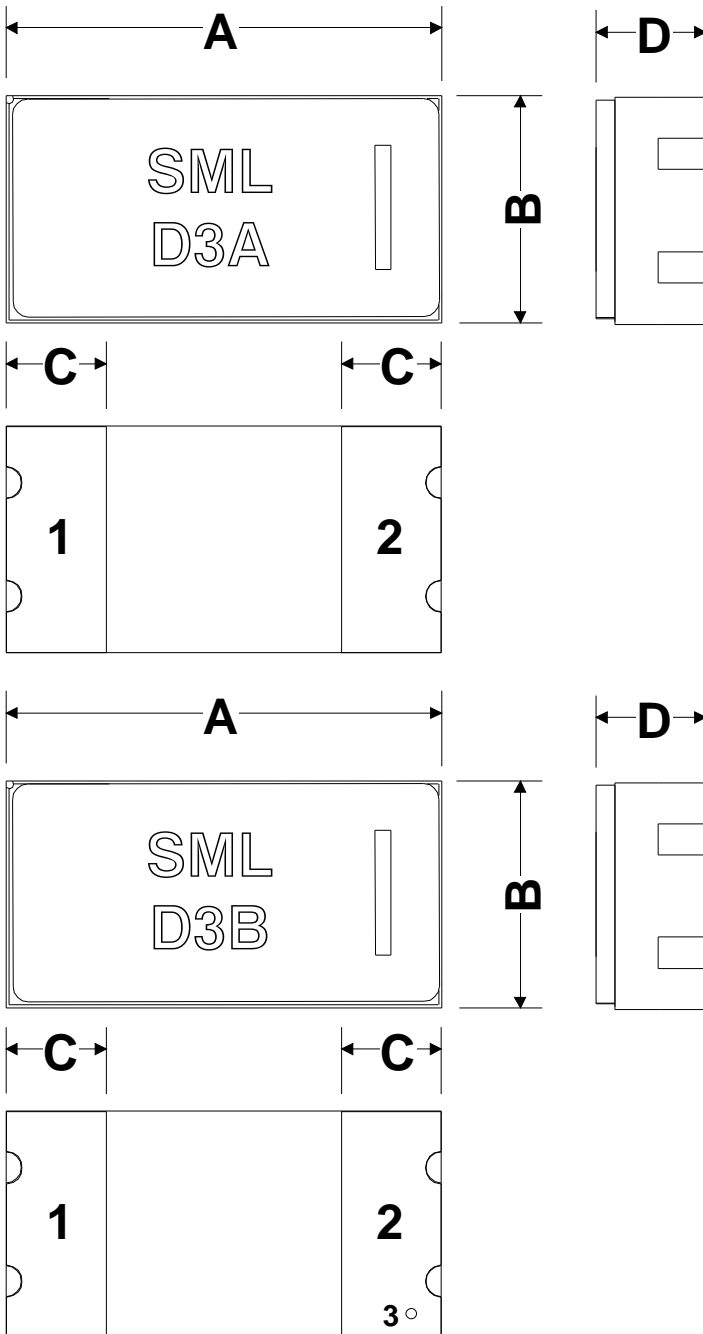
Semelab Limited reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by Semelab is believed to be both accurate and reliable at the time of going to press. However Semelab assumes no responsibility for any errors or omissions discovered in its use. Semelab encourages customers to verify that datasheets are current before placing orders.



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MECHANICAL DATA



DLCC3 Variant A (D3A)

PAD 1	ANODE	
PAD 2	CATHODE	
DIMENSION	mm	Inches
A	7.00 ±0.10	0.275 ±0.004
B	3.75 ±0.10	0.143 ±0.004
C	1.60 ±0.10	0.063 ±0.004
D	1.76 ±0.10	0.069 ±0.004

DLCC3 Variant B (D3B)

PAD 1	ANODE	
PAD 2	CATHODE	
PAD 3	LID CONTACT TO CATHODE*	
DIMENSION	mm	Inches
A	7.00 ±0.10	0.275 ±0.004
B	3.75 ±0.10	0.143 ±0.004
C	1.60 ±0.10	0.063 ±0.004
D	1.76 ±0.10	0.069 ±0.004

* The additional contact provides a connection to the lid in the application. Connecting the metal lid to a known electrical potential stops deep dielectric discharge in space applications; see the Space Weather link www.semelab.co.uk/dlcc3.html on the Semelab web site. Package variant to be specified at order.

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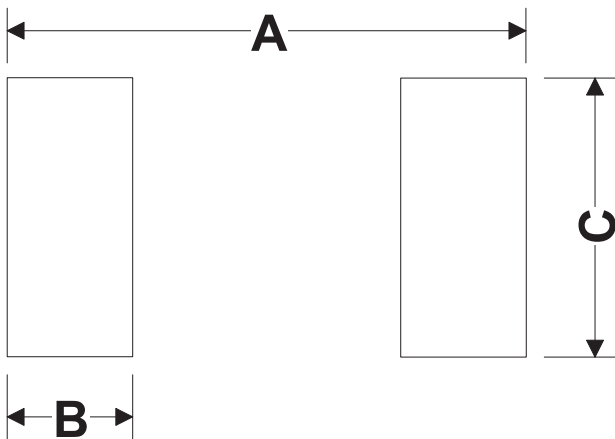
DLCC3 PCB SOLDER PAD LAYOUT GUIDE

The DLCC3 package is designed to align conveniently with the industry standard pad layout for the "MELF-5.7 (D-5B)" or "E-MELF" package.

The design allows easy substitution of the DLCC3 package into existing board designs providing easy surface mount process integration, excellent cost and availability benefits over MELF packages.

Soldering temperature should be 260°C for a maximum of 10 seconds.

The DLCC3 pad castellations allow solder flow up the sides of the package enabling visual inspection of the successful solder joint.



	Inches	mm
A	0.288	7.32
B	0.070	1.78
C	0.155	3.94

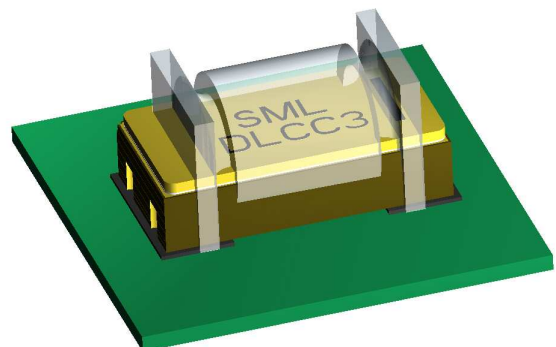


Image showing the DLCC3 on the recommended MELF-5.7 (D-5B) solder pad foot print and MELF-5.7 (D-5B) package overlay.

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SCREENING OPTIONS

Space Level (JQRS/ESA) and High Reliability options are available in accordance with the [High Reliability and Screening Options Handbook](#) available for download from the from the TT electronics Semelab web site.

ESA Quality Level Products are based on the testing procedures specified in the generic ESCC 5000 and in the corresponding part detail specifications.

Semelab's QR216 and QR217 processing specifications (JQRS), in conjunction with the companies ISO 9001:2000 approval present a viable alternative to the American MIL-PRF-19500 space level processing.

QR217 (Space Level Quality Conformance) is based on the quality conformance inspection requirements of MIL-PRF-19500 groups A (table V), B (table VIa), C (table VII) and also ESA / ESCC 5000 (chart F4) lot validation tests.

QR216 (Space Level Screening) is based on the screening requirements of MIL-PRF-19500 (table IV) and also ESA /ESCC 5000 (chart F3).

JQRS parts are processed to the device data sheet and screened to QR216 with conformance testing to Q217 groups A and B in accordance with MIL-STD-750 methods and procedures.

Additional conformance options are available, for example Pre-Cap Visual Inspection, Buy-Off Visit or Data Packs. These are chargeable and must be specified at the order stage (See Ordering Information). Minimum order quantities may apply.

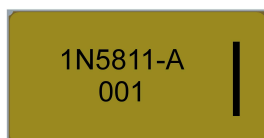
Alternative or additional customer specific conformance or screening requirements would be considered. Contact Semelab sales with enquires.

MARKING DETAILS

Parts can be laser marked with approximately 7 characters on two lines and always includes cathode identification. Typical marking would include part or specification number, week of seal or serial number subject to available space and legibility.

Customer specific marking requirements can be arranged at the time of order.

Example Marking:



ORDERING INFORMATION

Part numbers are built up from Type, Package Variant, and screening level. The part numbers are extended to include the additional options as shown below.

Type – See Electrical Stability Characteristics Table

Package Variant – See Mechanical Data

Screening Level – See Screening Options (ESA / JQRS)

Additional Options:

Customer Pre-Cap Visual Inspection	.CVP
Customer Buy-Off visit	.CVB
Data Pack	.DA
Solderability Samples	.SS
Scanning Electron Microscopy	.SEM
Radiography (X-ray)	.XRAY
Total Dose Radiation Test	.RAD
MIL-PRF-19500 (QR217)	
Group B charge	.GRPB
Group B destructive mechanical samples	.GBDM (12 pieces)
Group C charge	.GRPC
Group C destructive electrical samples	.GCDE (12 pieces)
Group C destructive mechanical samples	.GCDM (6 pieces)
ESA/ESCC	
Lot Validation Testing (subgroup 1) charge	.LVT1
LVT1 destructive samples (environmental)	.L1DE (15 pieces)
LVT1 destructive samples (mechanical)	.L1DM (15 pieces)
Lot Validation Testing (subgroup 2) charge	.LVT2
LVT2 endurance samples (electrical)	.L2D (15 pieces)
Lot Validation Testing (subgroup 3) charge	.LVT3
LVT3 destructive samples (mechanical)	.L3D (5 pieces)

Additional Option Notes:

1) All 'Additional Options' are chargeable and must be specified at order stage.

2) When Group B,C or LVT is required, additional electrical and mechanical destructive samples must be ordered

3) All destructive samples are marked the same as other production parts unless otherwise requested.

Example ordering information:

The following example is for the 1N5811D3 part with package variant B, JQRS screening, additional Group C conformance testing and a Data pack.

Part Numbers:

1N5811D3B-JQRS (Include quantity for flight parts)

1N5811D3B-JQRS.GRPC (chargeable conformance option)

1N5811D3B-JQRS.GCDE (charge for destructive parts)

1N5811D3B-JQRS.GCDM (charge for destructive parts)

1N5811D3B-JQRS.DA (charge for Data pack)

Customers with any specific requirements (e.g. marking or screening) may be supplied with a similar alternative part number (there is maximum 20 character limit to part numbers). Contact Semelab sales with enquiries.

High Reliability and Screening Options Handbook link: http://www.semelab.co.uk/pdf/misc/documents/hirel_and_screening_options.pdf